

CLAIMS

WE CLAIM:

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1. An integrated circuit (IC) card for use in a data processing device, comprising:
an IC package having multiple leads extending from said package;
3 a casing that encases said package, such that when said casing is inserted into
4 said data processing device, said leads provide an electrical interface between said IC
5 package and said data processing device without the use of a printed circuit board and
6 a connector.

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1 2. The IC card of claim 1 wherein said casing has a front surface having a front
opening, such that when said IC package is inserted into said casing, said IC package
and said data processing device form said electrical interface through said front
opening.

1 3. The IC card of claim 2 wherein said casing has a back surface having a back
2 opening [such that said IC package is inserted into said casing through said back
3 opening.]

1 4. The IC card of claim 3 wherein said casing has at least one stop at said back
2 opening such that when said IC package is fully inserted into said casing, said stop
3 holds said package securely within said casing.

1 5. The IC card of claim 2 wherein said casing has a bottom surface having a bottom
2 opening such that said IC package is inserted into said casing through said bottom
3 opening.

1 6. The IC card of claim 5 wherein said casing has at least one stop at said bottom
2 opening such that when said IC package is fully inserted into said casing, said stop
3 holds said package securely within said casing.

~~Set 1~~ 7. A method of assembling an integrated circuit (IC) card for use in a data
processing device, comprising the steps of:

3 providing an IC package, said package having multiple leads extending from said
4 package;
5 providing a casing; and,
6 inserting said package into said casing, such that when said casing is inserted
7 into said data processing device said leads provide an electrical interface between said
8 IC package and said data processing device without the use of a printed circuit board
9 and a connector.

~~Sub A~~ 8. The method of claim 7 wherein said step of providing a casing includes providing
2 a casing having a front surface with a front opening, such that when said IC package is
3 inserted into said casing, said IC package and said data processing device form said
4 electrical interface through said front opening.

1 9. The method of claim 8 wherein said step of providing a casing includes providing
2 a casing having a back surface with a back opening, and said step of inserting said IC
3 package includes inserting said IC package through said back opening of said casing.

1 10. The method of claim 9 where said step of providing a casing includes providing a
2 casing having at least one stop on said back opening such that when said IC package
3 is fully inserted into said casing through said back opening, said stop holds said IC
4 package securely within said casing

5 11. The method of claim 8 wherein said step of providing a casing includes providing
6 a casing having a bottom surface with a bottom opening, and said step of inserting said
7 IC package includes inserting said IC package through said bottom opening of said
8 casing.

1 12. The method of claim 11 wherein said step of providing a casing includes
2 providing a casing having at least one stop at said bottom opening such that when said
3 IC package is fully inserted into said casing through said bottom opening, said stop
4 holds said IC package securely within said casing.

1 13. A method of connecting an integrated circuit (IC) to a receptacle of a data
2 processing device, comprising the step of:
3 providing an IC package having multiple leads extending from said package;
4 and,

5 inserting said IC package into said data processing device such that said leads
6 from said IC package provide the electrical interface between said IC package and said
7 data processing device without the use of a printed circuit board or a connector.

1 14. The method of claim 13 wherein said step of providing an IC package includes
2 providing an IC package having a blade on pad socket device.

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